


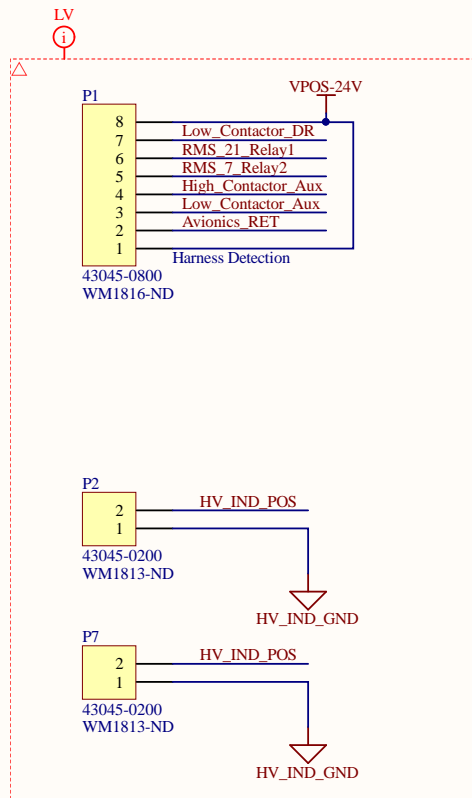
PRECHARGE

POD 5

REV 1

Title <i>Precharge</i>		Badgerloop Electrical 133 Engineering Research Building 1500 Engineering Drive Madison, Wi 53706		
Engineer: Shelby Riggleman	Revision:1			
Date: 2/13/2020	Time: 10:28:26 PM	Sheet 1 of		
File: precharge.SchDoc				

Precharge Board Connectors



MH1
4-40 Mount Hole

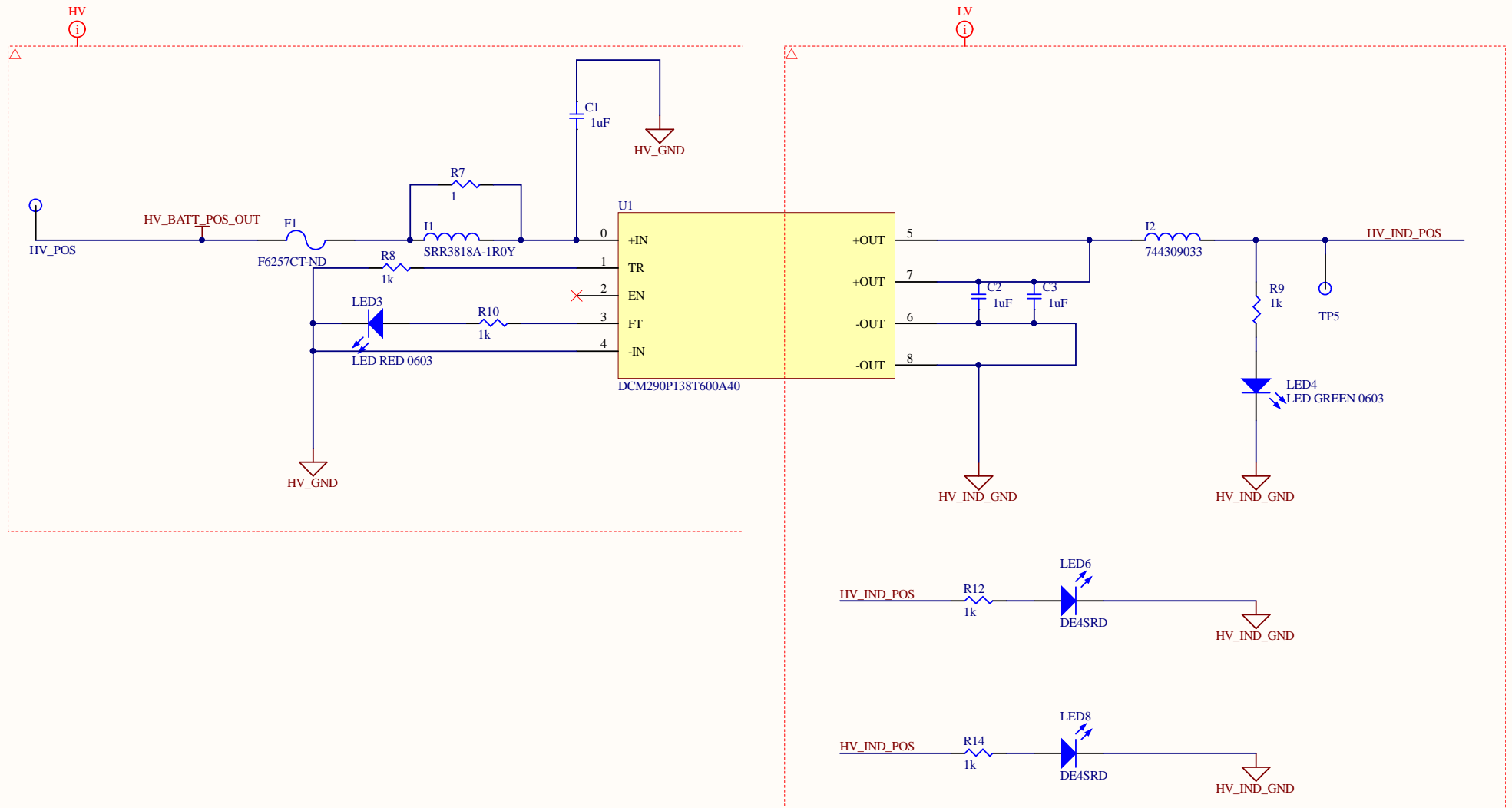
MH2
4-40 Mount Hole


MH3
4-40 Mount Hole

MH4
4-40 Mount Hole

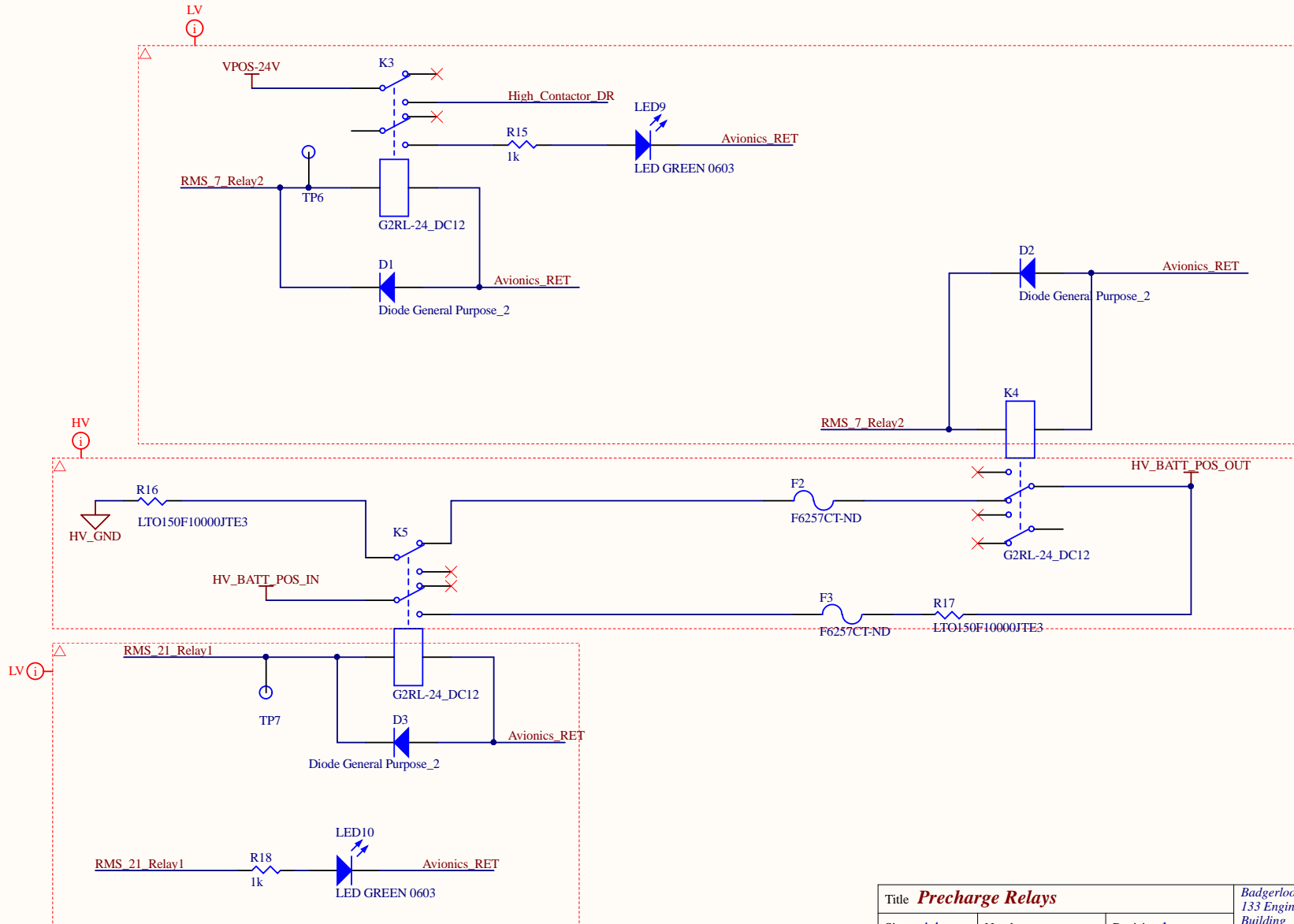
Title: Connectors		Badgerloop Electrical 133 Engineering Research Building 1500 Engineering Drive Madison, WI 53706	
Engineer: Shelby Riggleman	Revision: 1	<div> </div>	
Date: 2/13/2020	Time: 10:28:26 PM		
File: connectors.SchDoc		Sheet 2 of 2	


High Voltage Indicator Light



Title <i>HV Indicator Light</i>			Badgerloop 133 Engineering Research Building Madison, WI 53715	
Size: A4	Number:	Revision:1		
Date: 2/13/2020	Time: 10:28:26 PM Sheet 3 of			
File: C:\Users\Windows PC\Desktop\Badgerloop\git_repos\hardware\precharge\indicator_light.SchDoc				

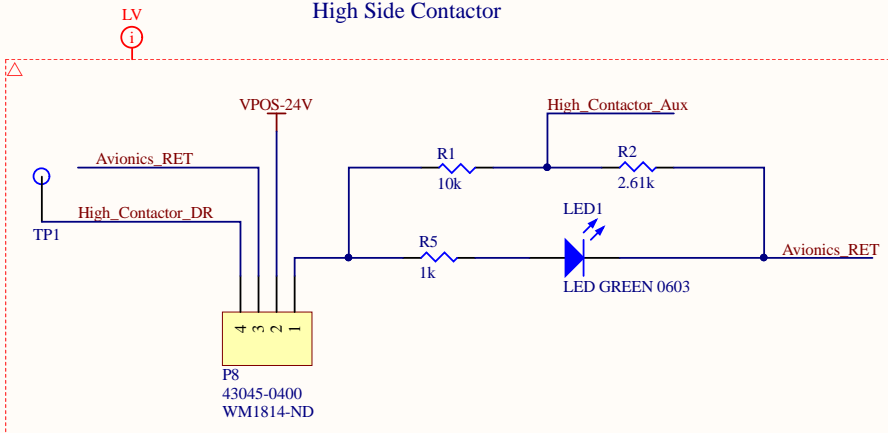
Precharge Relays



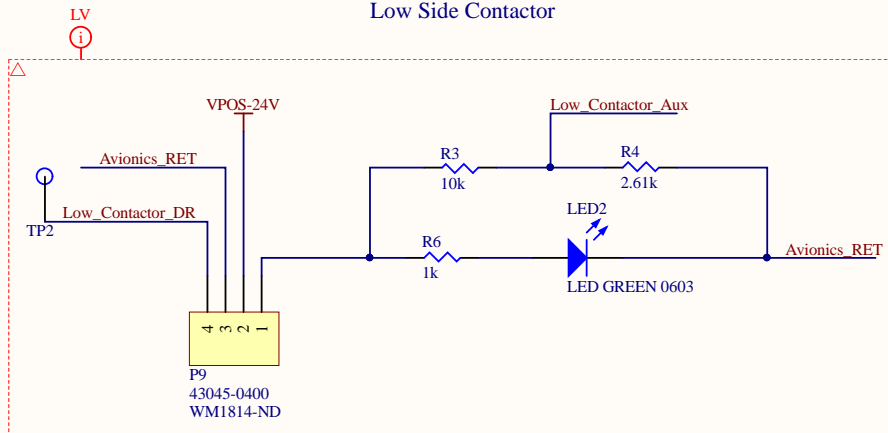
Title <i>Precharge Relays</i>			Badgerloop 133 Engineering Research Building Madison, WI 53715	
Size: A4	Number:	Revision:1		
Date: 2/13/2020	Time: 10:28:26 PM	Sheet 4 of		
File: C:\Users\Windows PC\Desktop\Badgerloop\git_repos\hardware\precharge\precharge_relays.SchDoc				

High Voltage Contactors

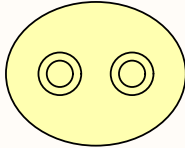
High Side Contactor



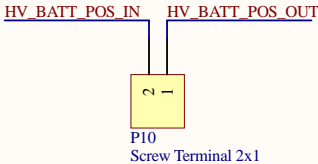
Low Side Contactor



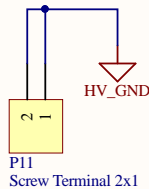
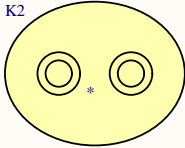
K1




Gigavac 200

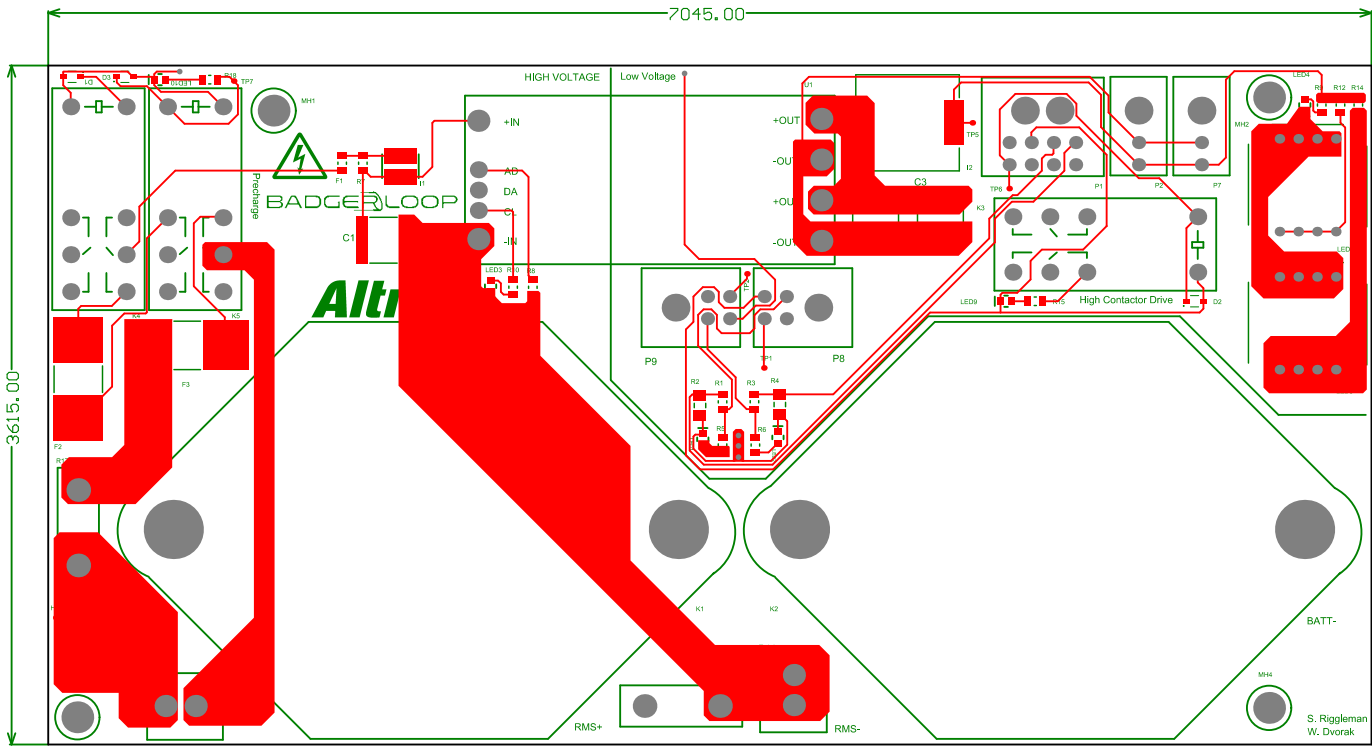


K2



Title <i>HV Contactors</i>			<i>Badgerloop</i> <i>133 Engineering Research</i> <i>Building</i> <i>Madison, WI 53715</i>	
Size: A4	Number:	Revision:1		
Date: 2/13/2020	Time: 10:28:26 PM	Sheet 5 of		
File: C:\Users\Windows PC\Desktop\Badgerloop\git_repos\hardware\precharge\Contactors.SchDoc				

Layer	Name	Material	Thickness	Constant	Board Layer Stack
1	Top Overlay				
2	Top Solder	Solder Resist	0.40mil	3.5	
3	Top Layer	Copper	1.40mil		
4	Dielectric 1	FR-4	12.60mil	4.8	
5	Internal Plane 1	Copper	1.40mil		
6	Dielectric2	FR-4	12.60mil	4.8	
7	Internal Plane 2	Copper	1.40mil		
8	Dielectric3	FR-4	12.60mil	4.8	
9	Bottom Layer	Copper	1.40mil		
10	Bottom Solder	Solder Resist	0.40mil	3.5	
11	Bottom Overlay				



**BADGER
LOOP**

Badgerloop
ERB Room 133
1400 Engineering Drive
Madison, WI 53706

ENGINEER:
SRiggleman, WDvorak

PCB DESIGNER:
SRiggleman, WDvorak

DATE:
2/13/2020

FILE NAME:
precharge.PcbDoc

TITLE:
precharge.PcbDoc

PART NO:
Precharge HV Board

DWG NO:

REV:
A

SCALE:
1:1

1

2

3

4

A

A

B

B

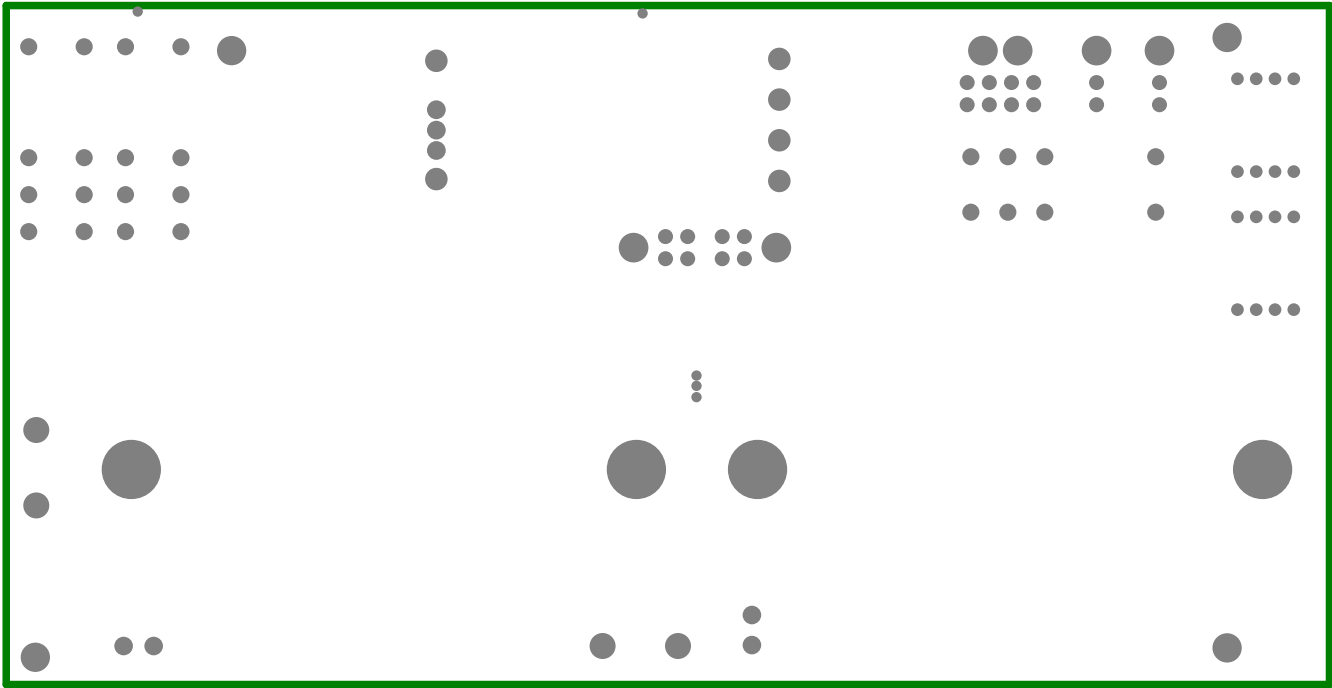
C

C

D

D

Layer	Name	Material	Thickness	Constant	Board Layer Stack
1	Top Overlay				
2	Top Solder	Solder Resist	0.40mil	3.5	
3	Top Layer	Copper	1.40mil		
4	Dielectric 1	FR-4	12.60mil	4.8	
5	Internal Plane 1	Copper	1.40mil		
6	Dielectric2	FR-4	12.60mil	4.8	
7	Internal Plane 2	Copper	1.40mil		
8	Dielectric3	FR-4	12.60mil	4.8	
9	Bottom Layer	Copper	1.40mil		
10	Bottom Solder	Solder Resist	0.40mil	3.5	
11	Bottom Overlay				



Internal Plane 1



Badgerloop
ERB Room 133
1400 Engineering Drive
Madison, WI 53706

ENGINEER:
SRiggleman, WDVorak

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precharge.PcbDoc

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precharge.PcbDoc

PART NO.:
Precharge HV Board

REV:
A

DWG NO:

SCALE:
1:1

1

2

3

4

A

A

B

B

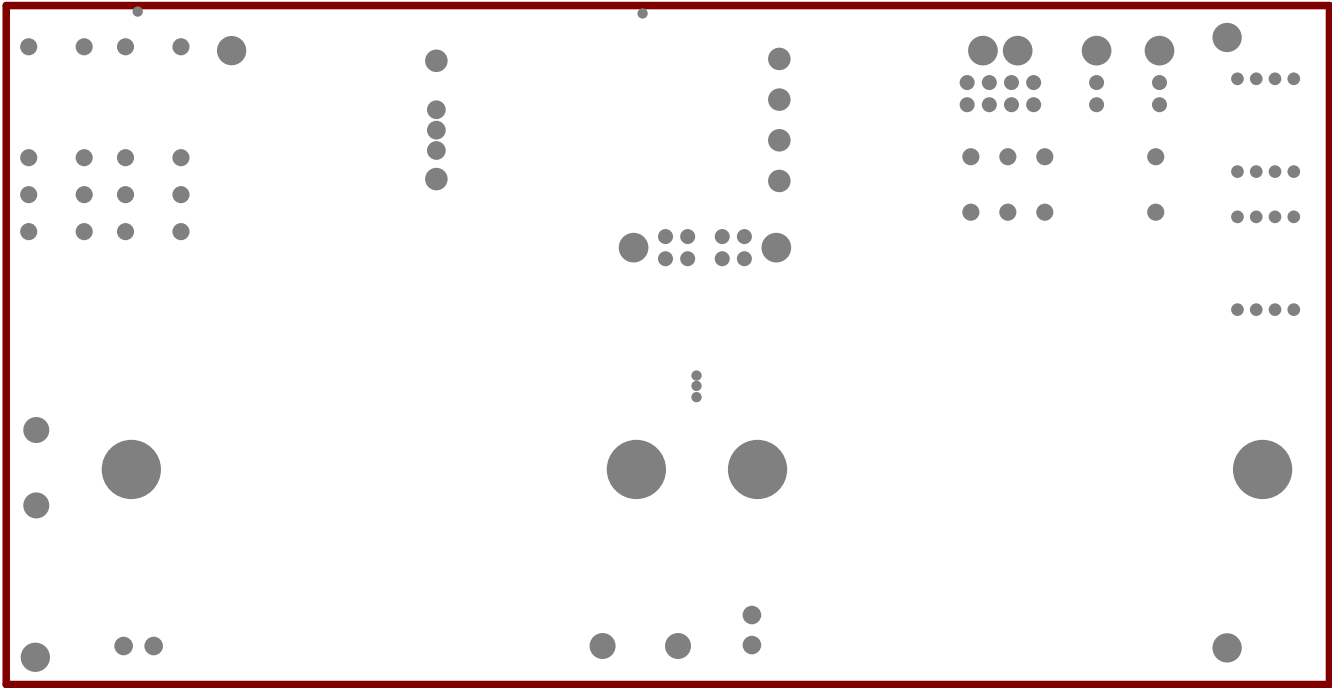
C

C

D

D

Layer	Name	Material	Thickness	Constant	Board Layer Stack
1	Top Overlay				
2	Top Solder	Solder Resist	0.40mil	3.5	
3	Top Layer	Copper	1.40mil		
4	Dielectric 1	FR-4	12.60mil	4.8	
5	Internal Plane 1	Copper	1.40mil		
6	Dielectric2	FR-4	12.60mil	4.8	
7	Internal Plane 2	Copper	1.40mil		
8	Dielectric3	FR-4	12.60mil	4.8	
9	Bottom Layer	Copper	1.40mil		
10	Bottom Solder	Solder Resist	0.40mil	3.5	
11	Bottom Overlay				



Internal Plane 2



Badgerloop
ERB Room 133
1400 Engineering Drive
Madison, WI 53706

ENGINEER:
SRiggleman, WDvorak

PCB DESIGNER:
SRiggleman, WDvorak

DATE:
2/13/2020

FILE NAME:
precharge.PcbDoc

TITLE:
precharge.PcbDoc

PART NO.:
Precharge HV Board

REV:
A

DWG NO:

SCALE:
1:1

1

2

3

4

A

A

B

B

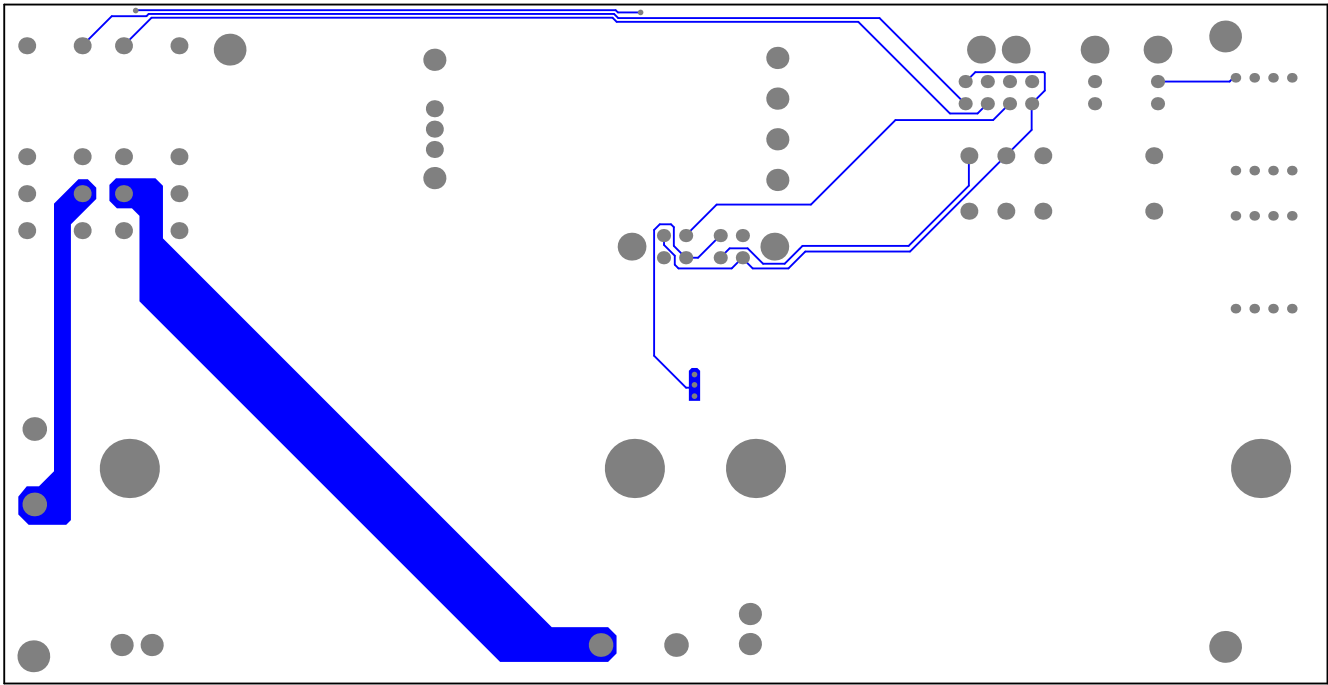
C

C

D

D

Layer	Name	Material	Thickness	Constant	Board Layer Stack
1	Top Overlay				
2	Top Solder	Solder Resist	0.40mil	3.5	
3	Top Layer	Copper	1.40mil		
4	Dielectric 1	FR-4	12.60mil	4.8	
5	Internal Plane 1	Copper	1.40mil		
6	Dielectric2	FR-4	12.60mil	4.8	
7	Internal Plane 2	Copper	1.40mil		
8	Dielectric3	FR-4	12.60mil	4.8	
9	Bottom Layer	Copper	1.40mil		
10	Bottom Solder	Solder Resist	0.40mil	3.5	
11	Bottom Overlay				



Badgerloop
ERB Room 133
1400 Engineering Drive
Madison, WI 53706

ENGINEER:
SRiggleman, WDvorak

PCB DESIGNER:
SRiggleman, WDvorak

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FILE NAME:
precharge.PcbDoc

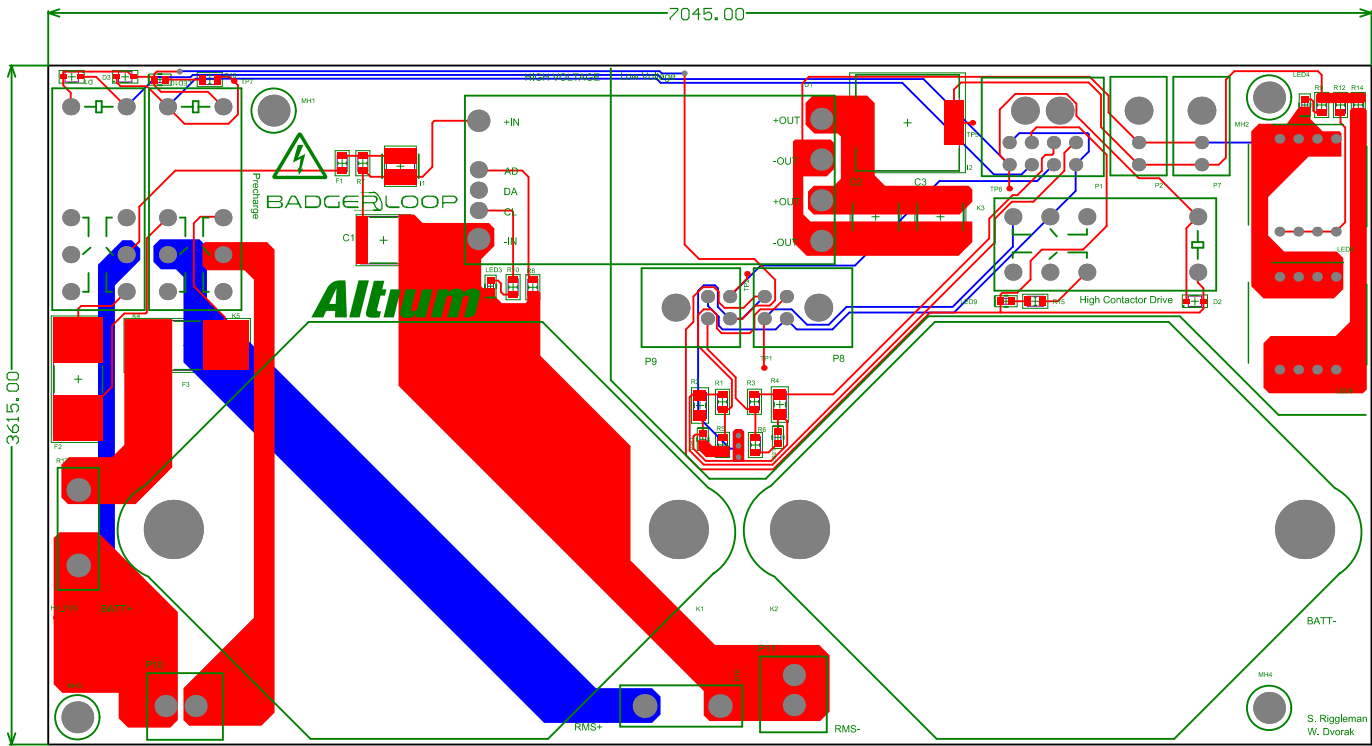
TITLE:
precharge.PcbDoc

PART NO.:
Precharge HV Board

REV:
A

DWG NO.:
SCALE:
1:1

Layer	Name	Material	Thickness	Constant	Board Layer Stack
1	Top Overlay				
2	Top Solder	Solder Resist	0.40mil	3.5	
3	Top Layer	Copper	1.40mil		
4	Dielectric 1	FR-4	12.60mil	4.8	
5	Internal Plane 1	Copper	1.40mil		
6	Dielectric2	FR-4	12.60mil	4.8	
7	Internal Plane 2	Copper	1.40mil		
8	Dielectric3	FR-4	12.60mil	4.8	
9	Bottom Layer	Copper	1.40mil		
10	Bottom Solder	Solder Resist	0.40mil	3.5	
11	Bottom Overlay				



**BADGER
LOOP**

Badgerloop
ERB Room 133
1400 Engineering Drive
Madison, WI 53706

ENGINEER:
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precharge.PcbDoc

PART NO:
Precharge HV Board

DWG NO:

REV:
A

SCALE:
1:1